





PNP SILICON HIGH VOLTAGE TRANSISTOR

2N 5415 2N 5416

TO-39 Metal Can Package RoHS compliant



TO-39

FEATURE:

1. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

APPLICATIONS:

High Speed Switching and Linear amplifier Appliances in Military, Industrial and Commercial Equipment.

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	2N5415	2N5416	UNIT
Collector Emitter Voltage	V_{CEO}	200	300	V
Collector Base Voltage	V_{CBO}	200	350	V
Emitter Base Voltage	V_{EBO}	4	6	V
Collector Current Continuous	I _C	1		Α
Base Current Continuous	I _B	0.5		Α
Power Dissipation @ Ta=50°C	Б	1		W
Derate Above 25°C	$ P_{D}$			mW/°C
Power Dissipation@ Tc=25°C	P _D 10		10	W
Derate Above 25°C	P_{D}	10		mW/°C
Junction Temperature	T _i	200		mW/ºC
Operating And Storage Junction Temperature Range	T _{stg}	-65 to +200		°C

THERMAL RESISTANCE

Junction to Ambient	$R_{th(j-a)}$	150	°C/W
Junction to Case	$R_{th(j-c)}$	17.5	°C/W



Continental Device India Pvt. Limited





An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		2N5415	2N5416	UNIT
Collector Emitter Breakdown Voltage	B _{VCEO(sus)} 1	$I_C=50$ mA, $I_B=0$	Min	200	300	V
Collector Cut off Current		V_{CB} =175V, I_{E} =0	Max	50		μΑ
Collector Cut on Current	I _{CBO}	V_{CB} =280V, I_{E} =0	Max	-	50	μΑ
Collector Cutoff Current	ı	V_{CE} =150V, I_{B} =0	Max	50		μΑ
Collector Cutoff Current	I _{CEO}	V_{CE} =250V, I_{B} =0	Max	-	50	μΑ
Emitter Cut off Current	1	V_{EB} =4V, I_{C} =0	Max	20		μΑ
Emilier Cut on Current	I _{EBO}	V_{EB} =6V, I_{C} =0	Max	1	20	μΑ
Collector Emitter Saturation Voltage	$V_{CE(Sat)}$	I_C =50mA, I_B =5mA	Max	2.5	2	V
Base Emitter Saturation Voltage	$V_{BE(Sat)}$	I_C =50mA, I_B =5mA	Max	1.5	1.5	V
DC Current Gain	h _{FE}	I_C =50mA, V_{CE} =10V		30-150	30-150	

DYNAMIC CHARACTERISTICS

Small Signal Current Gain	h _{fe}	I _C =5mA, V _{CE} =10V, f=1kHz	Min	25	25	
Transition Frequency	f _⊤	I _C =10mA, V _{CE} =10V, f=5MHz	Min	15	15	MHz
Output Capacitance	C _{ob}	V_{CB} =10V, $I_{E=0}$, f=1MHz	Max	15	15	pF
Input Capacitance	C_{ib}	$V_{EB}=V_{EBO}$ max, $I_{C}=0$, f=1MHz	Max	75	75	pF

Note:

- 1. Pulse Test: Pulse Width ≤300µs, Duty Cycle ≤2%
- 2. For PNP device voltage and current values will be negative (-).





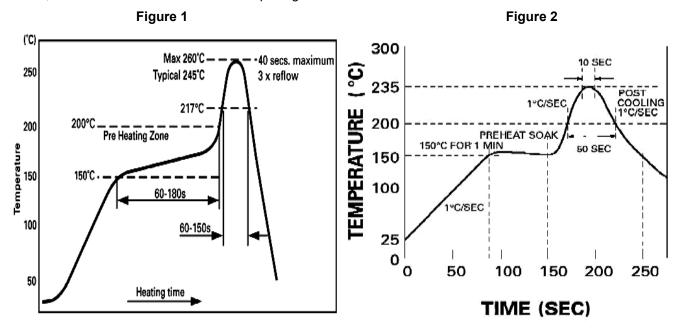


Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.



Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat - Temperature Range - Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above: – Temperature – Time	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.

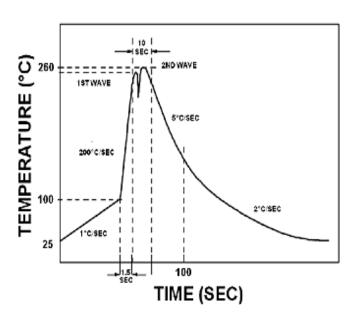




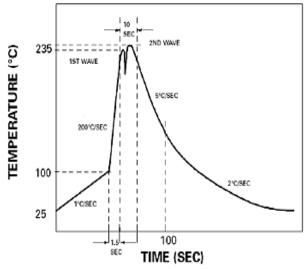


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max

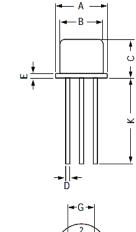






PACKAGE DETAILS

TO-39 Metal Can Package



DIM	MIN	MAX
Α	8.50	9.39
В	7.74	8.50
C	6.09	6.60
D	0.40	0.53
Е	-	0.88
F	2.41	2.66
G	4.82	5.33
Η	0.71	0.86
J	0.73	1.02
K	12.700	
L	42°	48°

1 2 3 Lu-\$

All dimensions are in mm

PIN CONFIGURATION

- 1. Emitter
- 2. Base
- 3. Collector



Packing Detail

PACKAGE	STANDARD PACK		INNER CARTO	CARTON BOX OUTER CARTON BOX		(
	Details	Net Weight/Qty	Size	Qtу	Size	Qty	Gr Wt
TO-39	500 pcs/polybag	540 gm/500 pcs	3" x 7.5" x 7.5"	20K	17" x 15" x 13.5"	32K	40 kgs







Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

	JEDEC MSL Level					
Level	Time	Condition				
1	Unlimited	≤30 °C / 85% RH				
2	1 Year	≤30 °C / 60% RH				
2a	4 Weeks	≤30 °C / 60% RH				
3	168 Hours	≤30 °C / 60% RH				
4	72 Hours	≤30 °C / 60% RH				
5	48 Hours	≤30 °C / 60% RH				
5a	24 Hours	≤30 °C / 60% RH				
6	Time on Label(TOL)	≤30 °C / 60% RH				







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



Continental Device India Pvt. Limited

CIN No. U32109DL1964PTC004291